

Section

MV Semi-conductor

ApplicationField
Laboratory**PRODUCT BENEFITS**

No silicon needed
 Fine tuning of the blade with a 'click' for each 1/10 mm
 Very smooth finish over the insulation
 Adjustable length of semiconductor cutback : 25-30-40 mm / 0,984-1,181-1,575 in

TOOL CAPACITY

Diameter	18 - 60 mm 0,709 - 2,362 inch
Thickness capacity	1,8 mm / 0,071 in
Angle of the chamfer on the semiconductor	13°
Remaining length of the semiconductor	25-30-40 mm / 0,984-1,181-1,575 in

TOOL DIMENSIONS

Length	235 mm
Width	125 mm
Height	90 mm
Weight without box	0,85 Kg
Packaging	None

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Tool to remove bonded semiconductor with chamfer on the semiconductor cutback

TO DO WHAT

The CWB/18-60-FEP enables the user to easily remove the bonded semi-conductor with a chamfer on the transition, leaving a very smooth finish over the insulation
 The CWB 18-60 works without silicone

**Options**

SGM - Large size pouch

Spare part

LCWB-FEP - Spare blade for bonded semiconductor with chamfer 13°

LCWB-FEP-V - Spare blade for bonded semiconductor with chamfer 13° + screw

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protection pouch

PG3HTA/2530 - Pliers for MV cables outer sheath

BRMRD1E - Tool to remove insulation

MV cables Tools

CWB/18-60-FEP



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Thickness capacity	Angle of the chamfer on the semiconductor	Remaining length of the semiconductor	Length	Width	Height	
CWB/18-60	18 - 60 mm 0,709 - 2,362 in	1,1 mm / 0,043 in	8°	25-30-40 mm / 0,984-1,181-1,575 in	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	none
CWB/18-60-FEP	18 - 60 mm 0,709 - 2,362 in	1,8 mm / 0,071 in	13°	25-30-40 mm / 0,984-1,181-1,575 in	235 mm 9,252 in	125 mm 4,921 in	90 mm 3,543 in	none